

Interaction of Ammonium Sulfide with the Semiconductor Surfaces of AlSb and Related Alloys

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Outline

- Application
- Previous passivation studies
- Experiment
- Results
 - Surface Morphology by SEM
 - Energy Dispersive X-Ray Spectroscopy
 - Electrical characteristics
- Summary

Application: Gamma radiation detection

Advantages

- wide energy bandgap
- high carrier mobilities
- high atomic number

 **High resolution, room temperature gamma detection**

Problems

- rapid oxidation of aluminum
- high volatility of antimony
- reaction of molten AlSb with most crucible materials

 **Growth of bulk AlSb in single crystal form is difficult**

Studies of epitaxial Al(As)Sb for radiation detection

High-Resistivity Semi-insulating AlSb on GaAs Substrates Grown by Molecular Beam Epitaxy

E.I. VAUGHAN^{1,3} S. ADDAMANE,² D.M. SHIMA,² G. BALAKRISHNAN,² and A.A. HECHT[†]

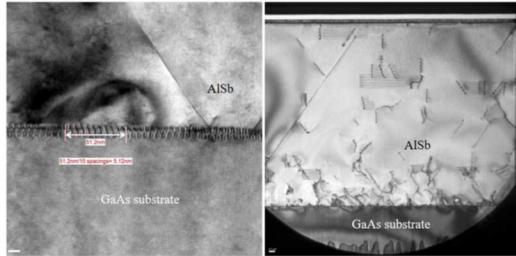
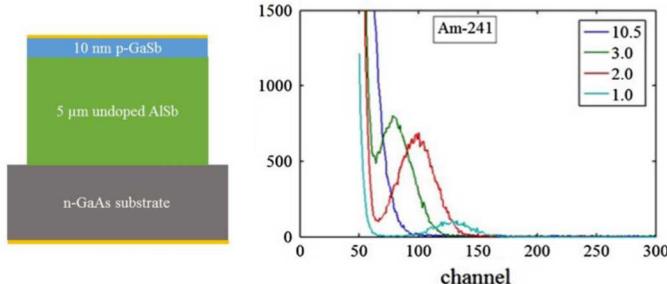


Fig. 1. TEM images of AlSb on GaAs, with higher resolution on left to show lattice dislocation spacing.

E. I. Vaughan, et. al., *J. Electron Mater* **45**, 2025 (2016).



E. I. Vaughan. "Thin film AlSb carrier transport properties and room temperature radiation response." UNM (2016).

Energy-Sensitive GaSb/AlAsSb Separate Absorption and Multiplication Avalanche Photodiodes for X-Ray and Gamma-Ray Detection

Bor-Chau Juang, Andrew Chen, Dingkun Ren, Baolai Liang,[‡] David L. Prout, Arion F. Chatzioannou, and Diana L. Huffaker

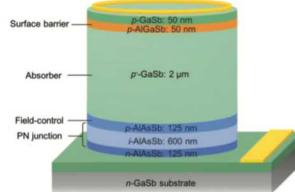
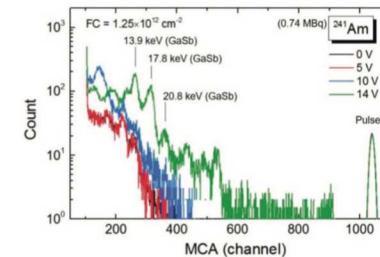


Figure 1. Schematic diagram of the GaSb/AlAsSb SAM-APD structure with a 2 μ m GaSb absorber.



B. Juang, et. al., *Adv. Opt. Mater.* **190010** (2019).

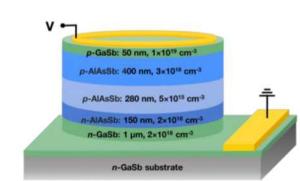
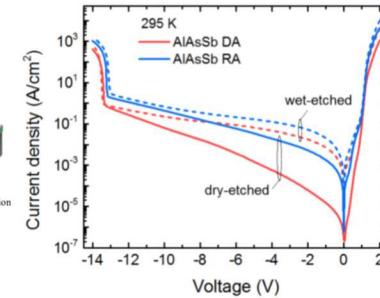


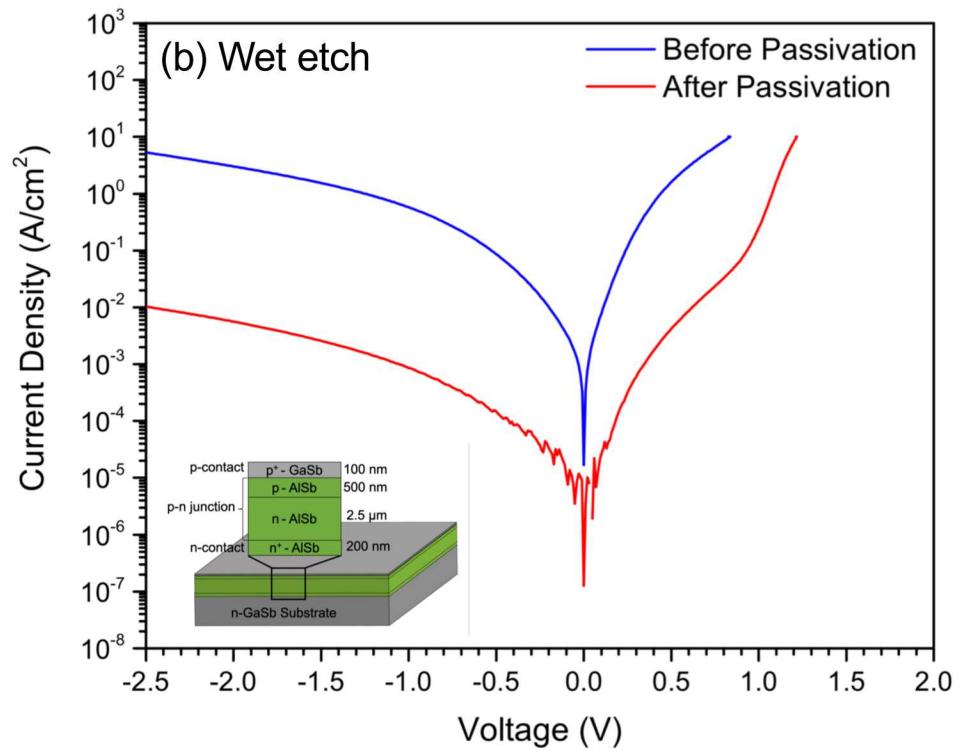
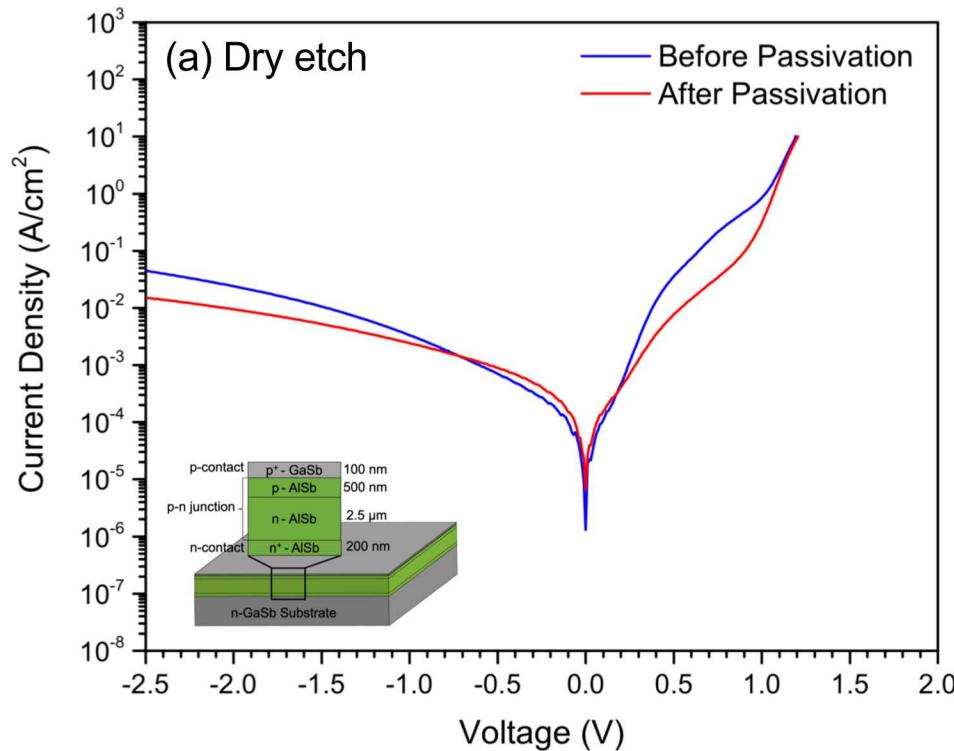
Figure 5-10 The AlAsSb PIN device structure with a 280 nm i-region



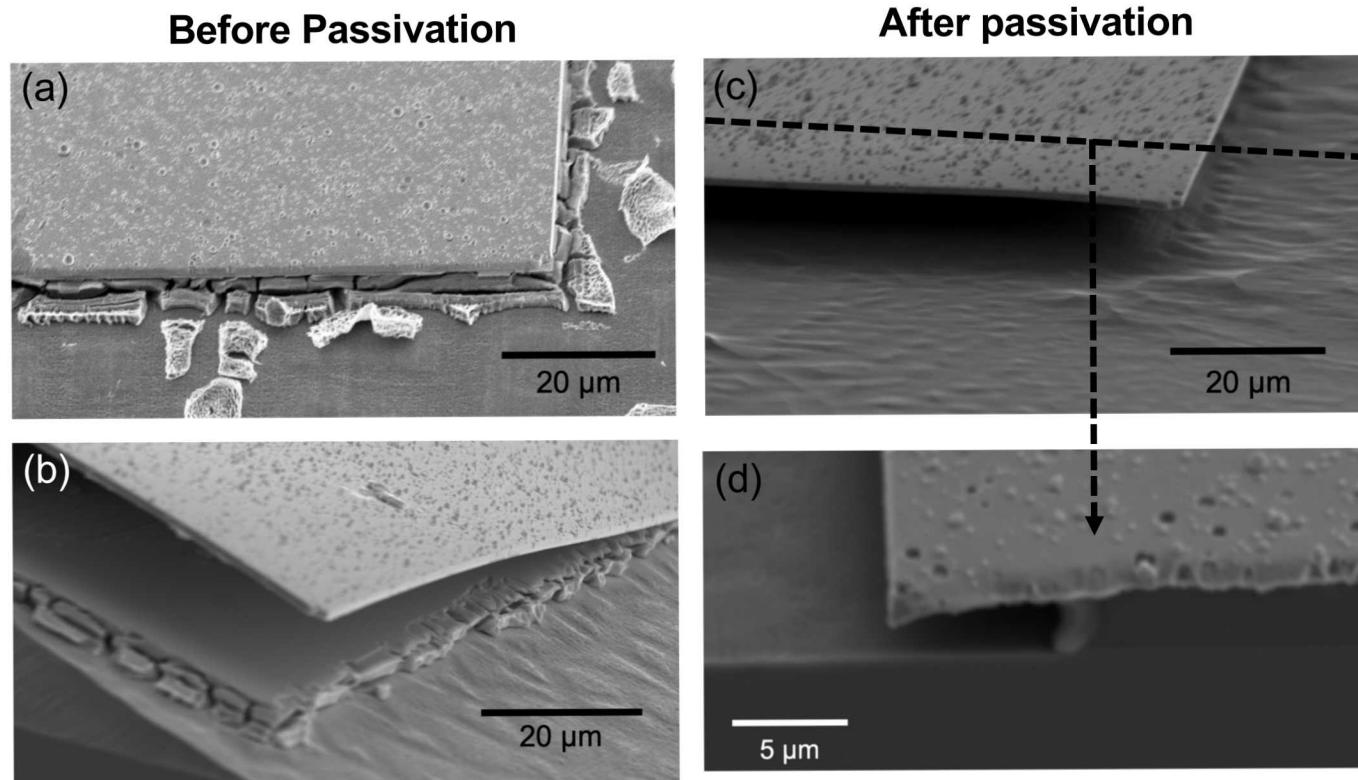
B. Juang. "Development of Antimonide-based Energy-sensitive Radiation Detectors." PhD diss., UCLA, (2018).



p-n AlSb diode passivated with full strength ammonium sulfide

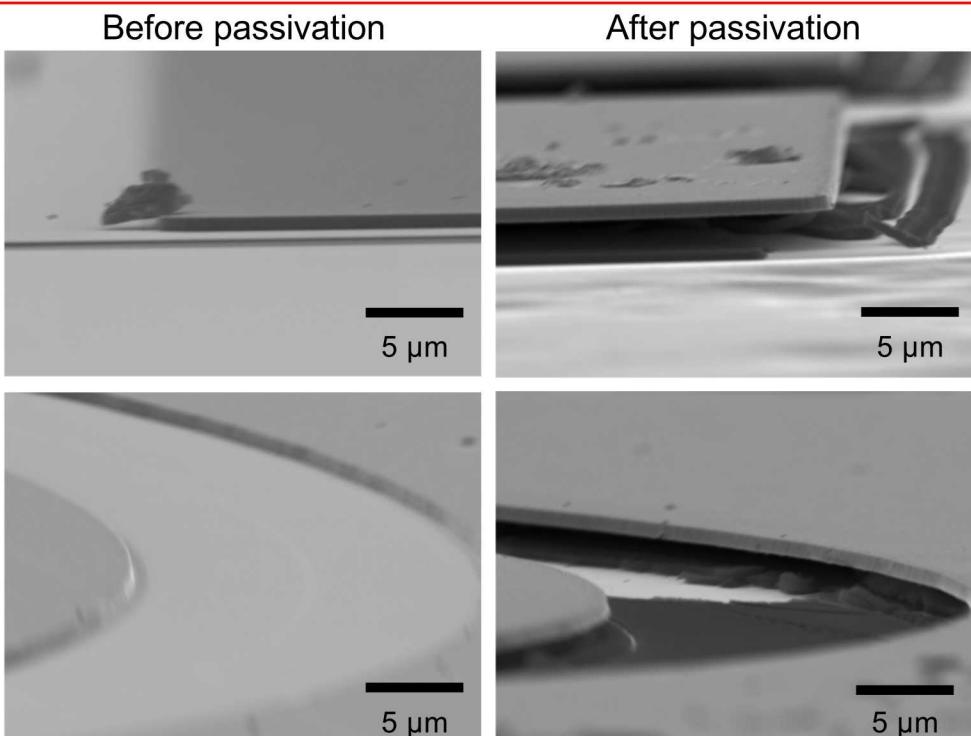
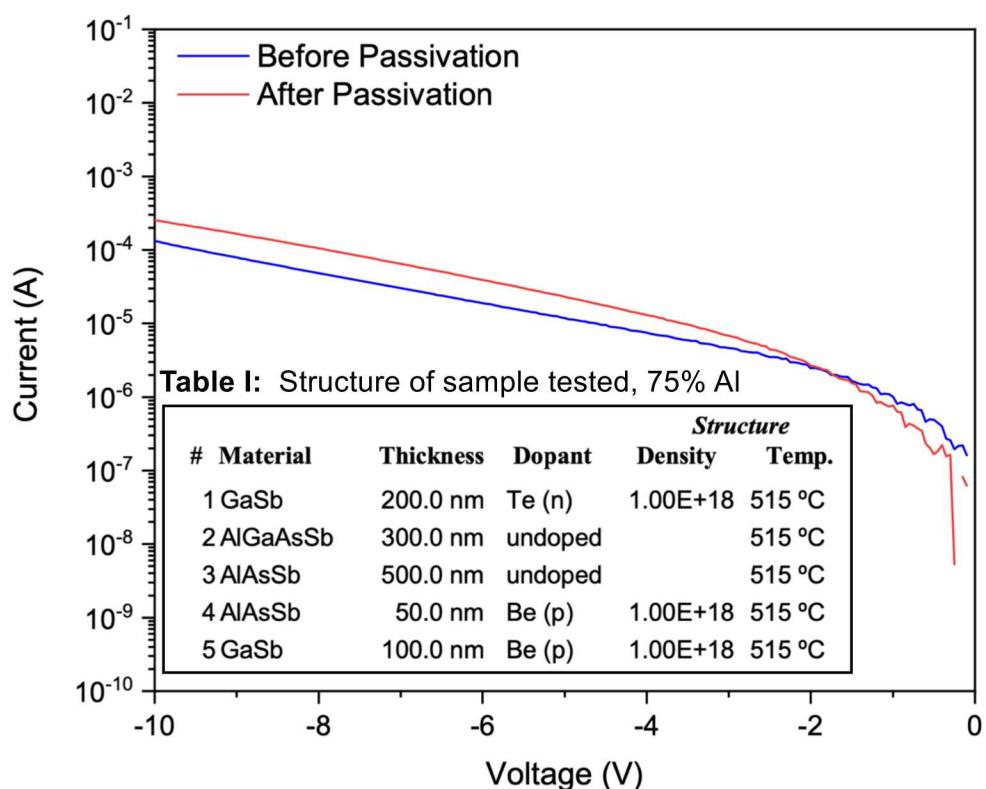


Surface morphology of devices isolated by wet etch



Samples were passivation with 40-44% aqueous ammonium sulfide solution for 5 min at a temperature of 60 °C

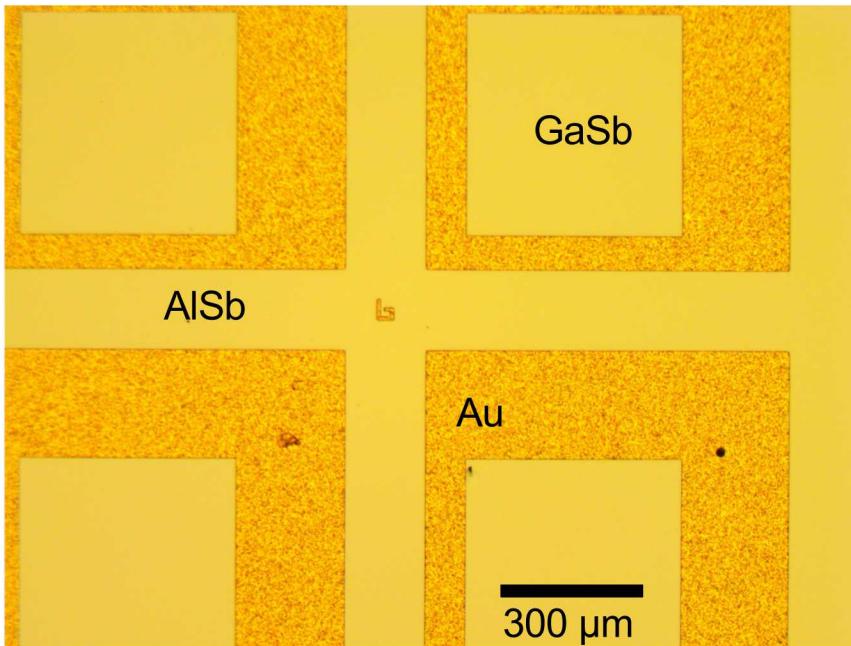
GaSb/AlGaAsSb/AlAsSb p-i-n diode with mesas defined by dry etch and passivated with full strength ammonium sulfide



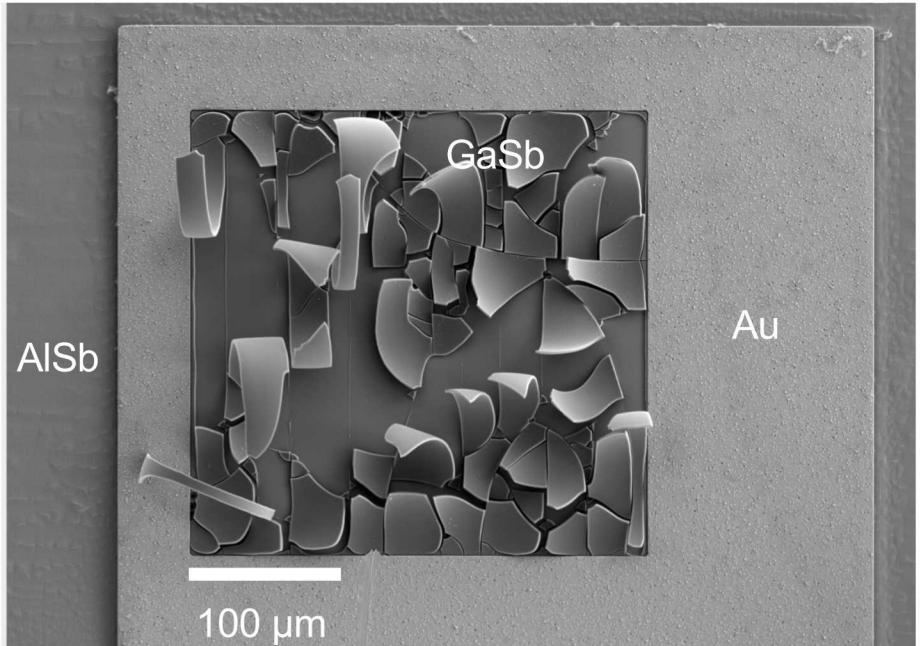
Samples were passivation with 40-44% aqueous ammonium sulfide solution for 5 min at a temperature of 60 °C

Effect of full strength ammonium sulfide on GaSb surfaces

Before passivation



After passivation



Passivation Study with Diluted Ammonium Sulfide at Room Temperature



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Structure studied

EB6830

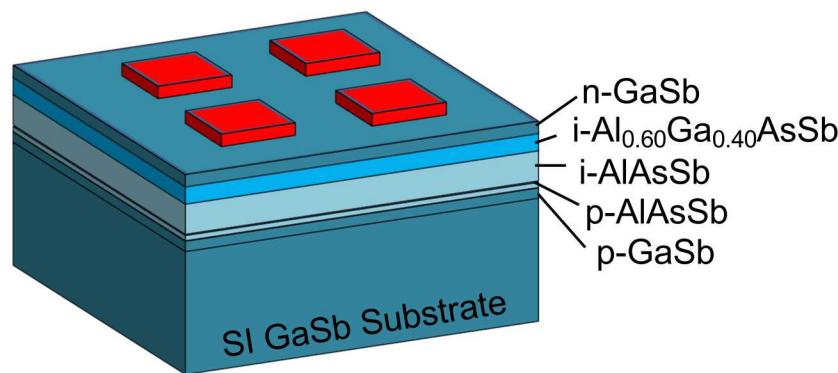
#	Material	<i>Structure</i>					Comment
		Thickness	Dopant	Density	Temp.	SL	
1	GaSb	200.0 nm	Te (n)	1.00E+18	515 °C		
2	AlGaAsSb	300.0 nm	undoped		515 °C		nominally 60% Al
3	AlAsSb	500.0 nm	undoped		515 °C		
4	AlAsSb	50.0 nm	Be (p)	1.00E+18	515 °C		
5	GaSb	100.0 nm	Be (p)	1.00E+18	515 °C		



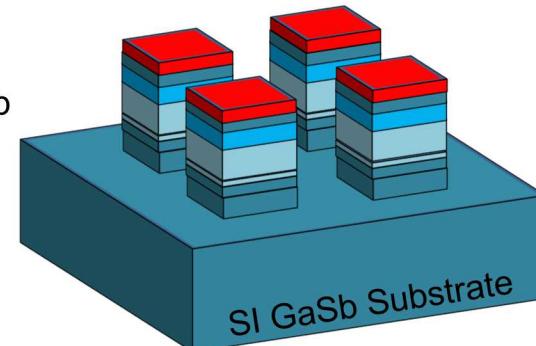
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Experiment

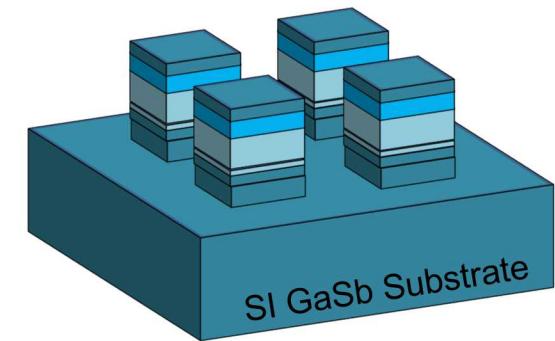
1.- Patterned samples with squares of 50 μm x 50 μm



2.- ICP etch with BCl_3 gas to a depth of $\sim 3 \mu\text{m}$



3.- Passivation with diluted ammonium sulfide solution for 5 min at room temperature



ammonium sulfide with isopropanol
 $(\text{NH}_4)_2\text{S:C}_3\text{H}_8\text{O}$

ammonium sulfide with water
 $(\text{NH}_4)_2\text{S:H}_2\text{O}$

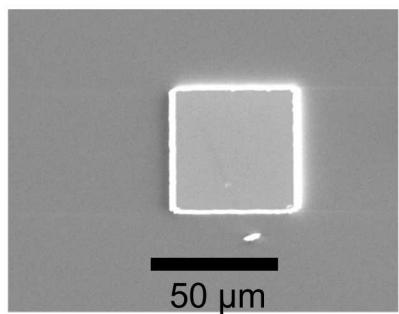
Concentrations:
1:5, 1:10, 1:20



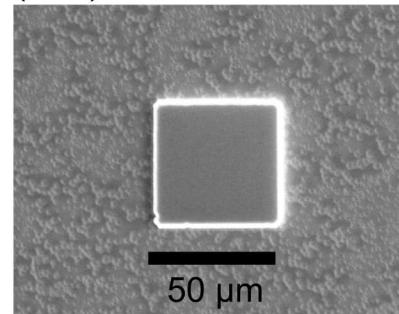
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Surface morphology of passivated samples

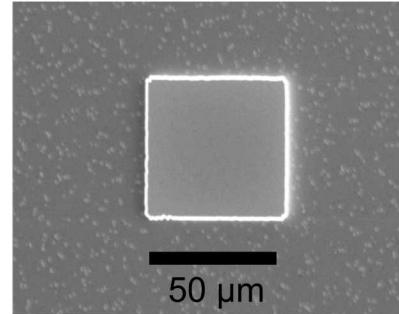
Un - passivated



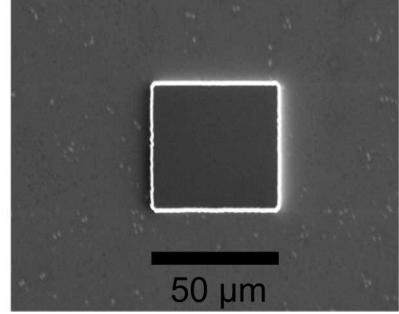
$(\text{NH}_4)_2\text{S:C}_3\text{H}_8\text{O}$ 1:5



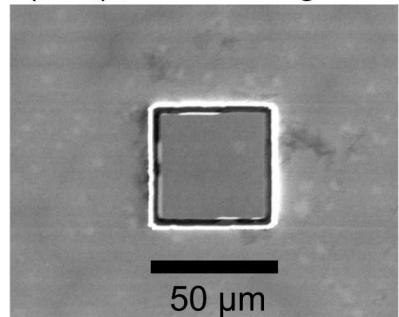
$(\text{NH}_4)_2\text{S:C}_3\text{H}_8\text{O}$ 1:10



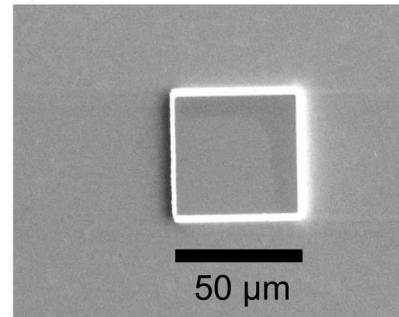
$(\text{NH}_4)_2\text{S:C}_3\text{H}_8\text{O}$ 1:20



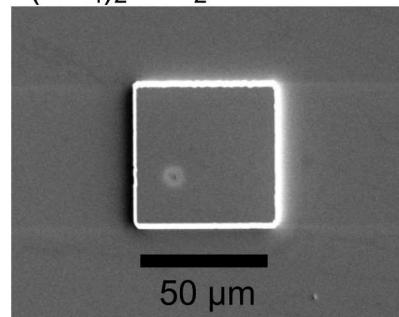
$(\text{NH}_4)_2\text{S}$ Full strength



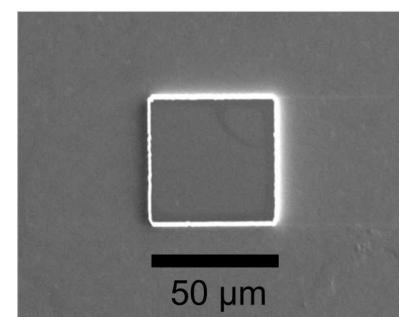
$(\text{NH}_4)_2\text{S:H}_2\text{O}$ 1:5



$(\text{NH}_4)_2\text{S: H}_2\text{O}$ 1:10

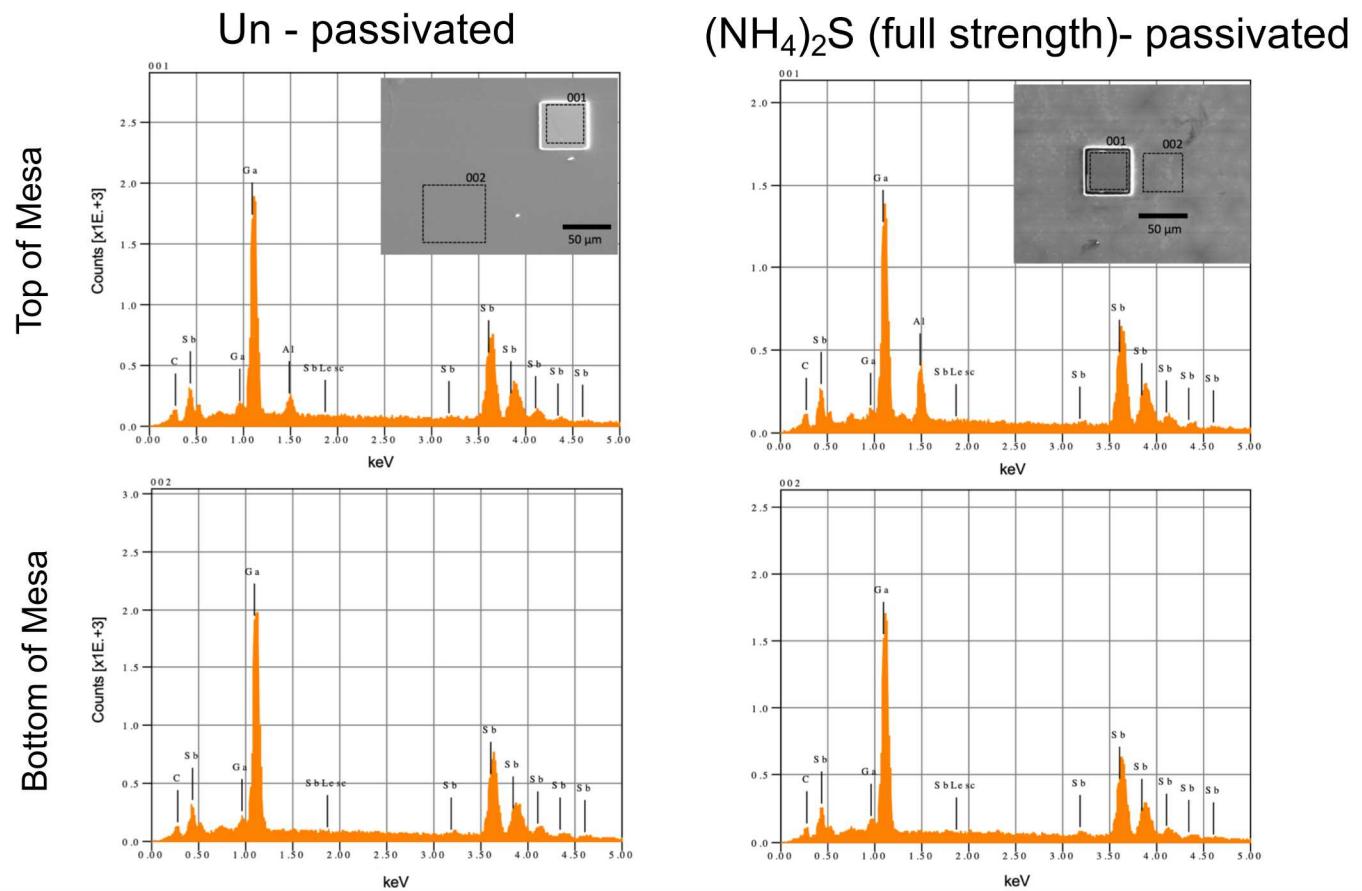


$(\text{NH}_4)_2\text{S: H}_2\text{O}$ 1:20



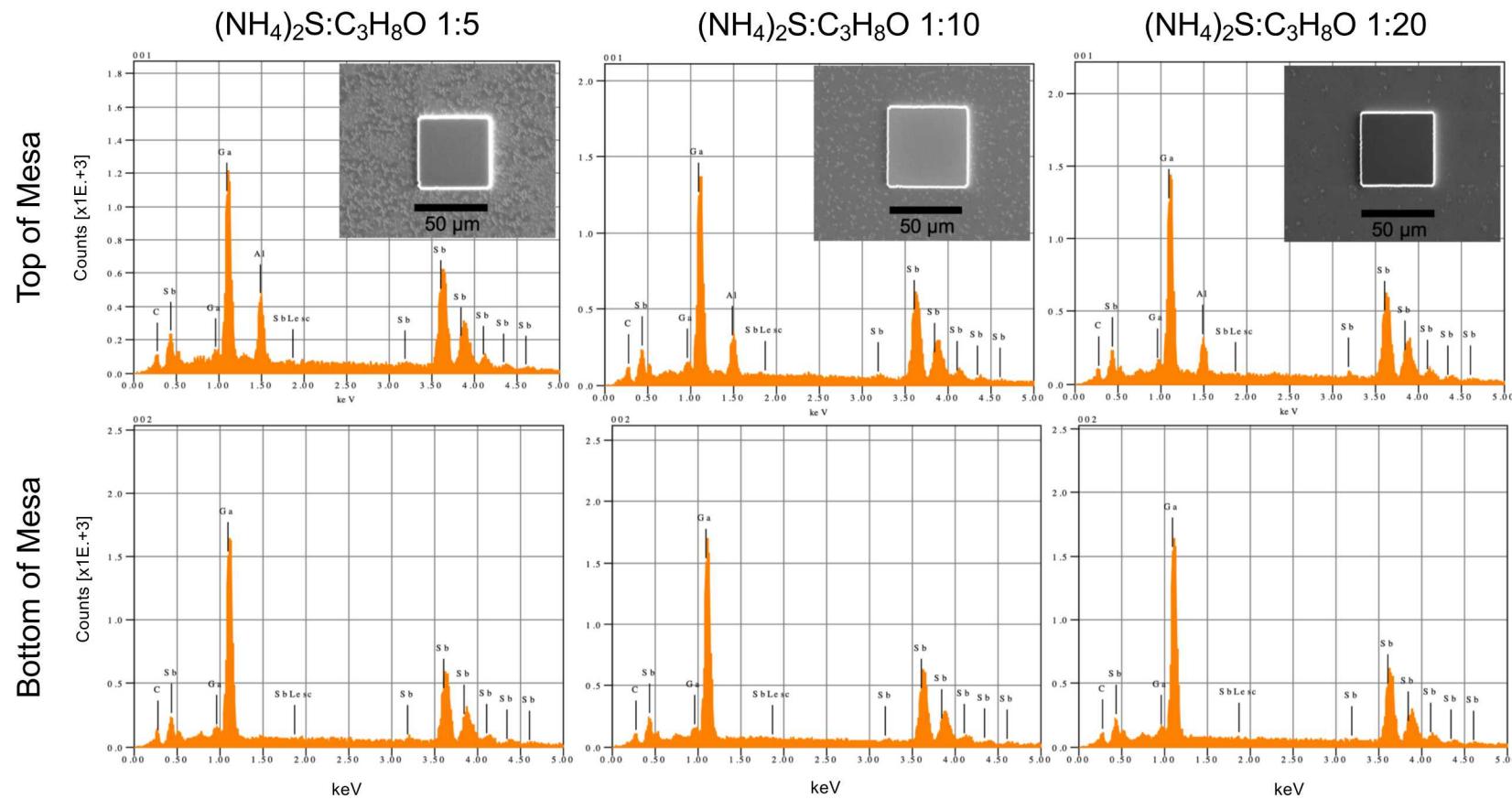
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Energy Dispersive x-Ray Spectroscopy (EDS) Analysis



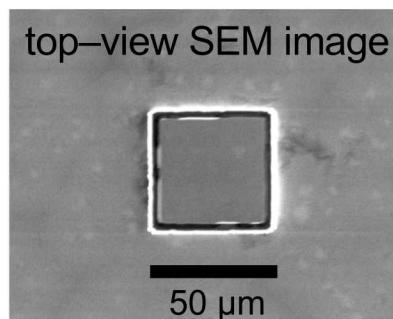
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EDS of samples passivated with alcohol diluted ammonium sulfide



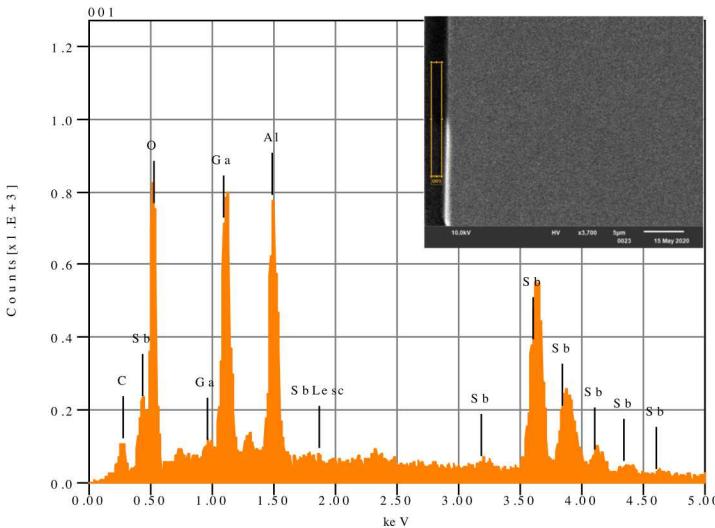
Effect of room temperature full strength $(\text{NH}_4)_2\text{S}$ passivation on GaSb

(NH₄)₂S (full strength)- passivated



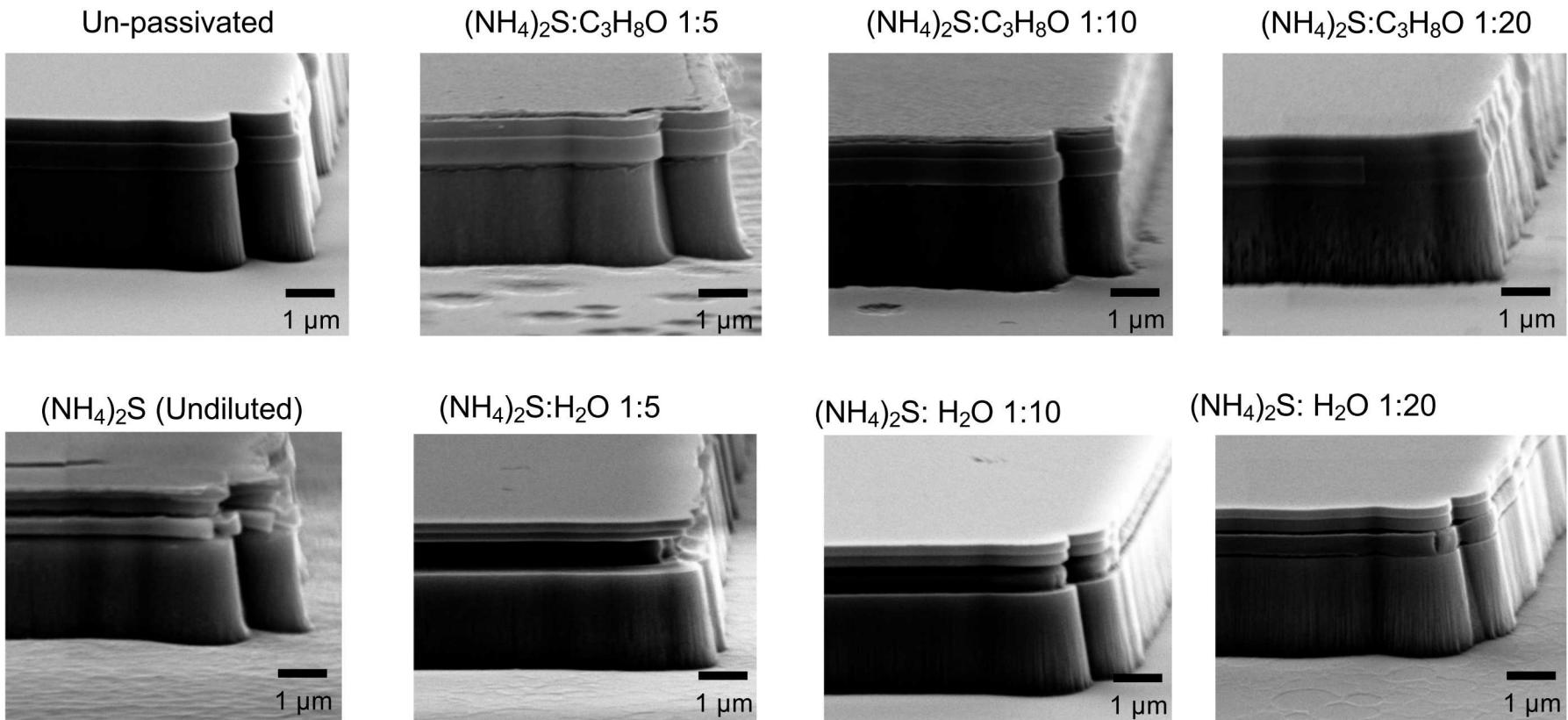
A scanning electron micrograph (SEM) showing a rectangular microfluidic channel. The channel is a shallow, rectangular depression in a substrate, with a slightly raised rim around the perimeter. The surface of the channel appears relatively smooth but with some fine, irregular features. The image is taken at a 45-degree tilt, giving it a three-dimensional appearance. A scale bar in the bottom right corner indicates 20 micrometers.

EDS from the edge of the mesa



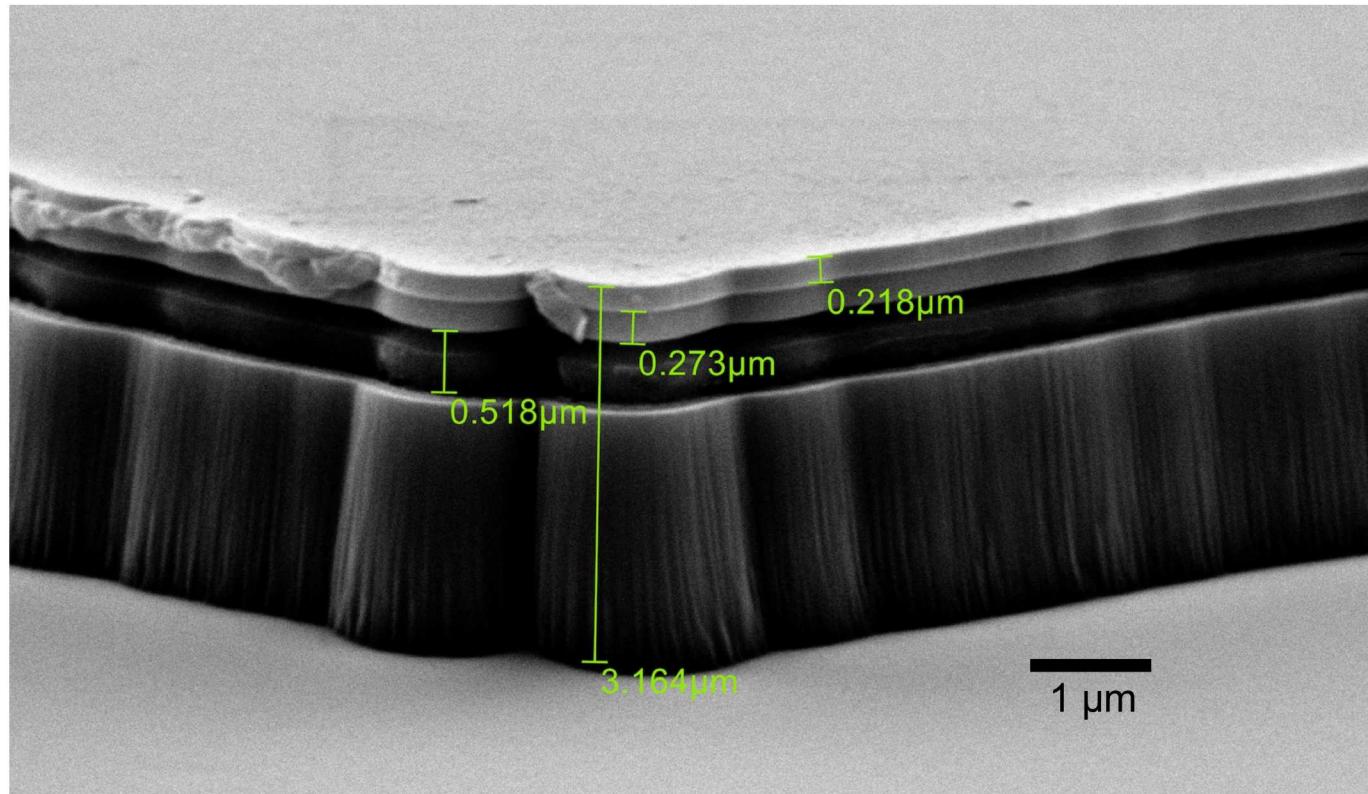
The EDS, besides the typical Al, Ga, and Sb peaks, shows an Oxygen peak which means oxidation. Oxidation is the beginning of etch process.

Morphology of sample's sidewalls



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$(\text{NH}_4)_2\text{S}$: H_2O 1:10

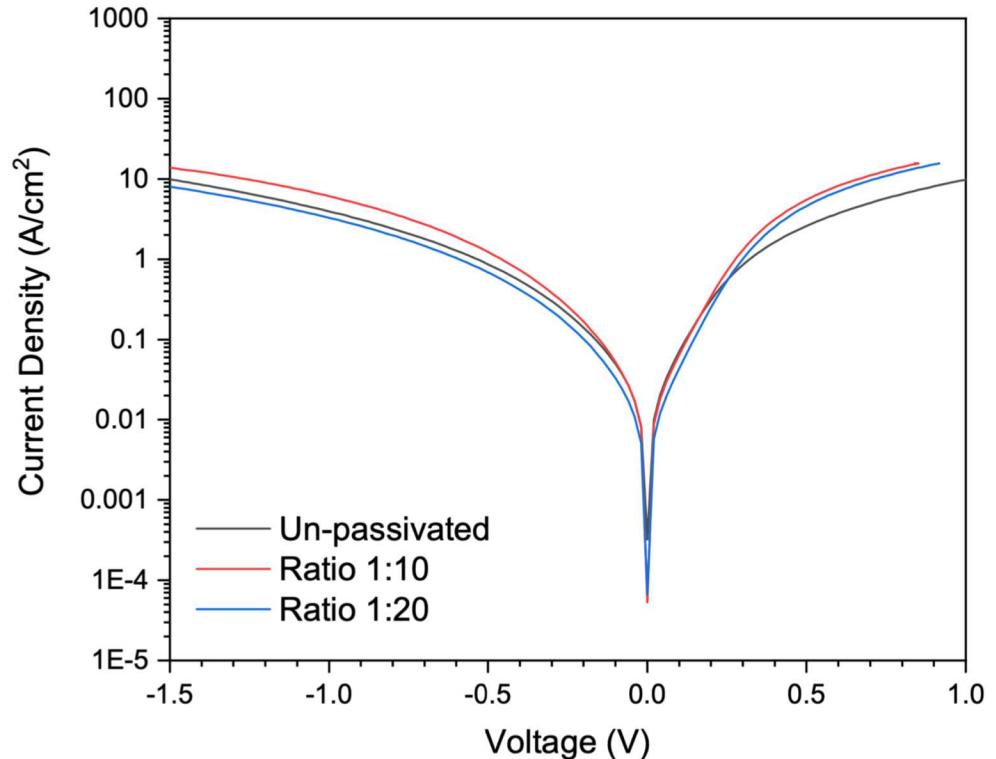
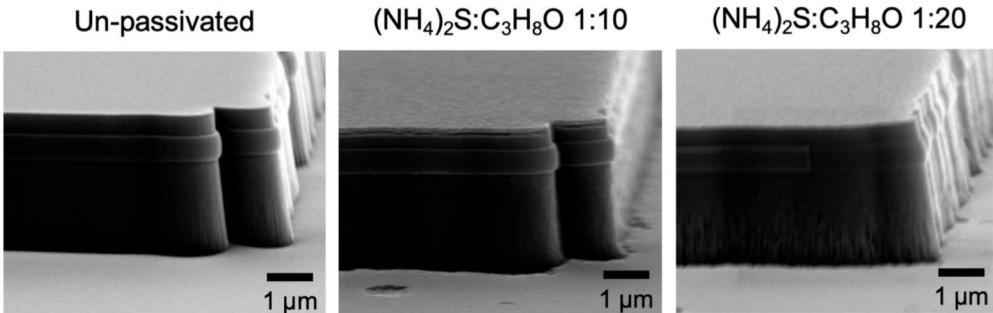
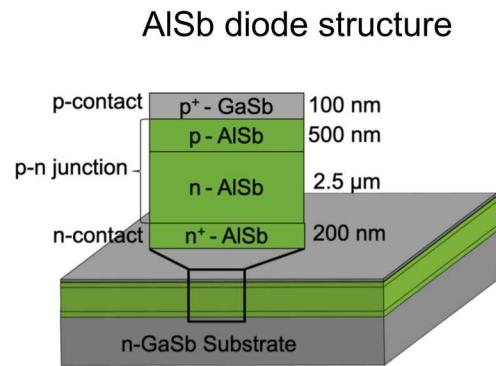


#	Material	Thickness	Dopant
1	GaSb	200.0 nm	Te (n)
2	AlGaAsSb	300.0 nm	undoped
3	AlAsSb	500.0 nm	undoped
4	AlAsSb	50.0 nm	Be (p)
5	GaSb	100.0 nm	Be (p)



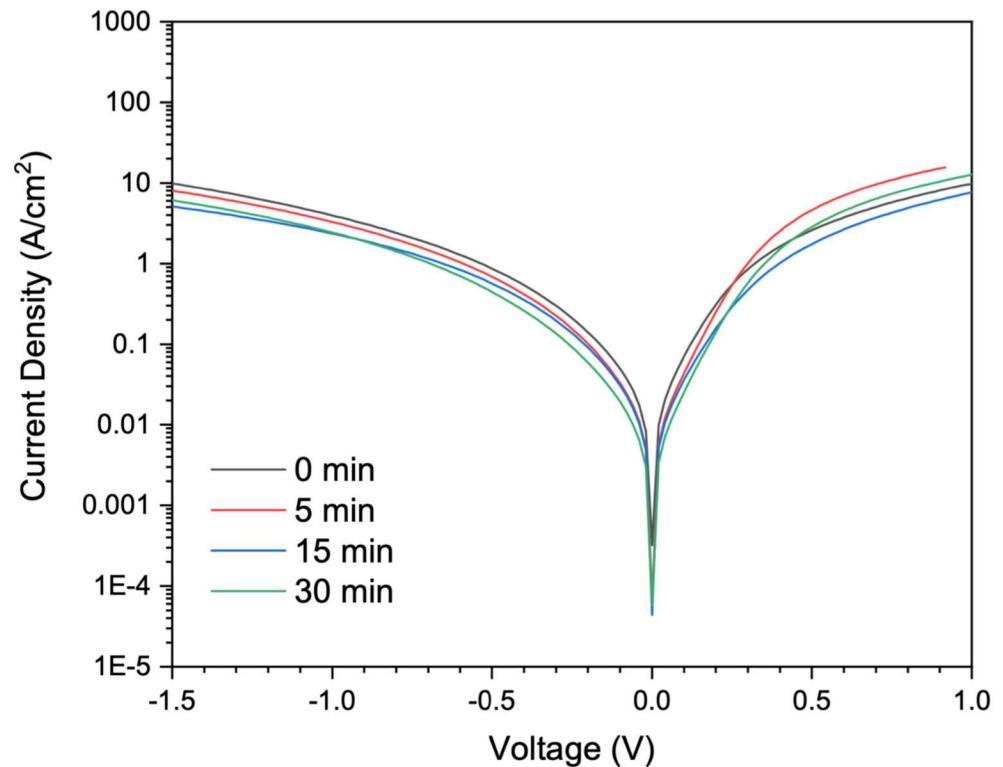
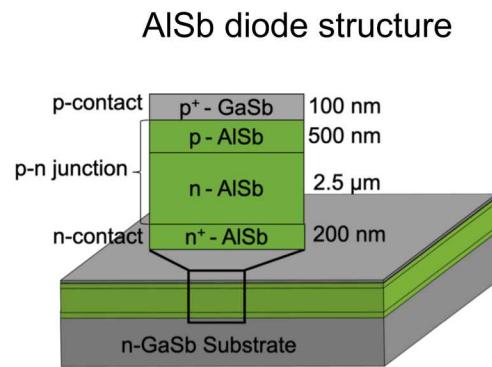
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Best passivation for an AlSb diode



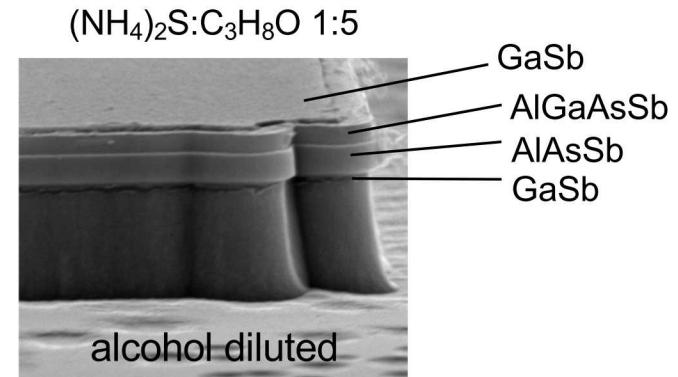
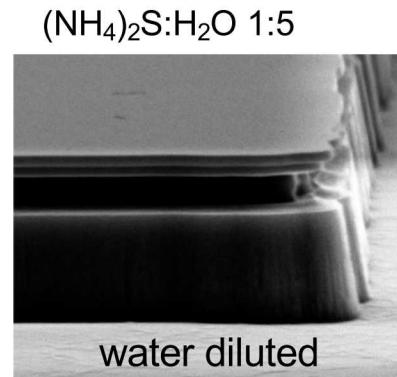
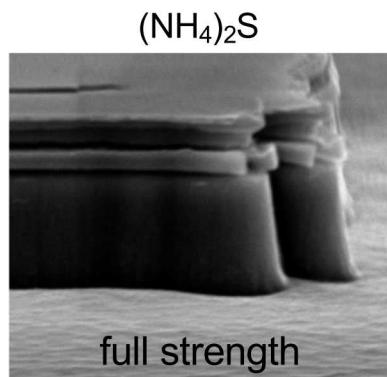
Current-Voltage characteristics of AlSb diodes passivated at different ammonium sulfide concentrations

Effect of time in the solution



Current-Voltage characteristics of AlSb diodes passivated with $(\text{NH}_4)_2\text{S:C}_3\text{H}_8\text{O}$ 1:20 for different times

Summary



- Passivation with **full strength ammonium sulfide** at **room temperature** is **less aggressive** than when at 60 °C.
- Passivation with **water diluted** ammonium sulfide is the **best option** when structure is mostly **GaSb**.
- Passivation with **alcohol diluted** ammonium sulfide is the **best option** when structure has **AlSb alloys**.

Acknowledgments

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